100% Material Declaration Data Sheet for 7 Series FGG484 Package

PK610 (v1.0) Sept 10, 2013

Average Weight: 2.2960 g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.048674**	**2.120%**
	Silicon	7440-21-3	100.00		0.048674	
Die Attach Material					**0.008859**	**0.386%**
	Silver	7440-22-4	77.50		0.006866	
	Bismaleimide monomer	Trade Secret	15.00		0.001329	
	Acrylate monomer	Trade Secret	7.50		0.000664	
Mold Compound					**1.125465**	**49.019%**
	Solid Epoxy Resin	Trade Secret	5.00		0.056273	
	Phenol Resin	Trade Secret	3.00		0.033764	
	Phenol Novolac	9003-35-4	3.00		0.033764	
	Metal Hydroxide	Trade Secret	3.00		0.033764	
	Carbon Black	1333-86-4	0.30		0.003376	
	Silica fused	60676-86-0	70.40		0.792327	
	Silicon Dioxide	7631-86-9	15.00		0.168820	
	Silica, crystalline	14808-60-7	0.30		0.003376	
Copper Wire					**0.006997**	**0.305%**
	Copper	7440-50-8	98.25		0.006875	
	Palladium	7440-05-3	1.75		0.000122	
Solder Ball					**0.404317**	**17.610%**
	Tin (Sn)	7440-31-5	96.50		0.390166	
	Silver (Ag)	7440-22-4	3.00		0.012130	
	Copper (Cu)	7440-50-8	0.50		0.002022	
Substrate					**0.701689**	**30.561%**
	Gold (Au)	7440-57-5	1.99		0.013964	
	Nickel (Ni)	7440-02-0	6.09		0.042733	
	Copper Foil	7440-50-8	7.65		0.053679	
	Copper Plating	7440-50-8	37.77		0.265028	
	Continuous Filament Fiber Glass	65997-17-3	10.16		0.071292	
	Non halogen fire retardant	Trade Secret	0.01		0.000070	
	BT Core	Trade Secret	30.50		0.214015	
	Solder Mask	Trade Secret	5.83		0.040908	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/10/13	1.0	Initial Xilinx release.

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